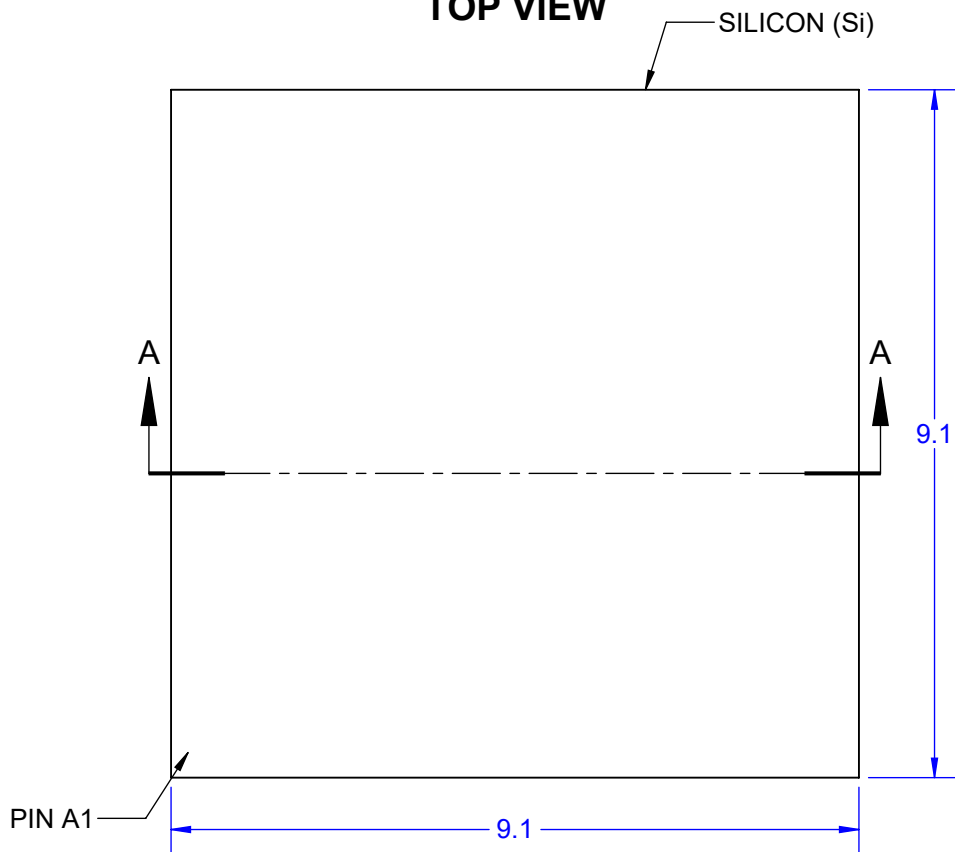
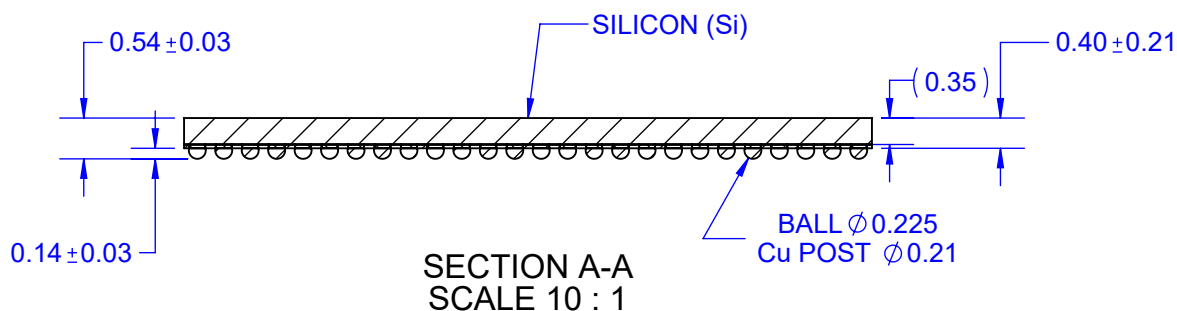
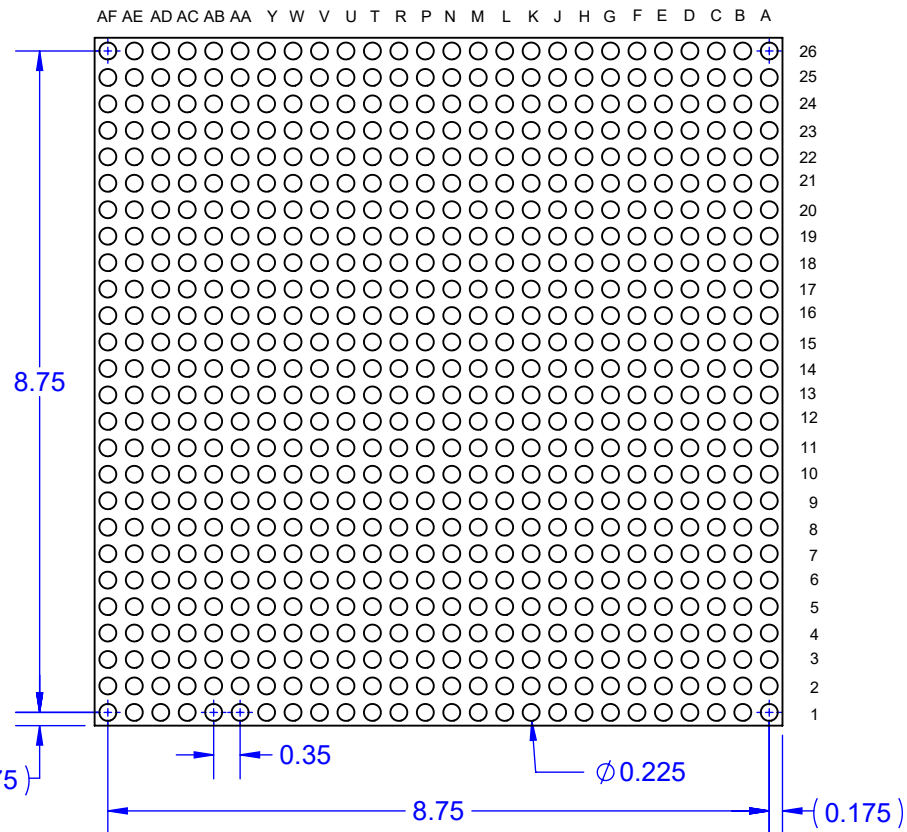


TOP VIEW




BALL VIEW



Notes: (Unless Otherwise Specified).

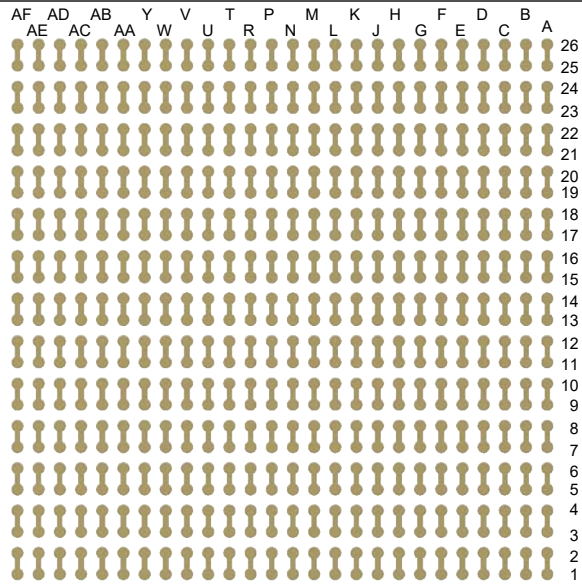
- 1) DIMENSIONS: mm
- 2) SOLDER BALL ALLOY: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW) $\phi 0.225\text{mm} \pm 0.03$.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: $\phi 0.21\text{mm}$.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP676T.35C-DC260D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

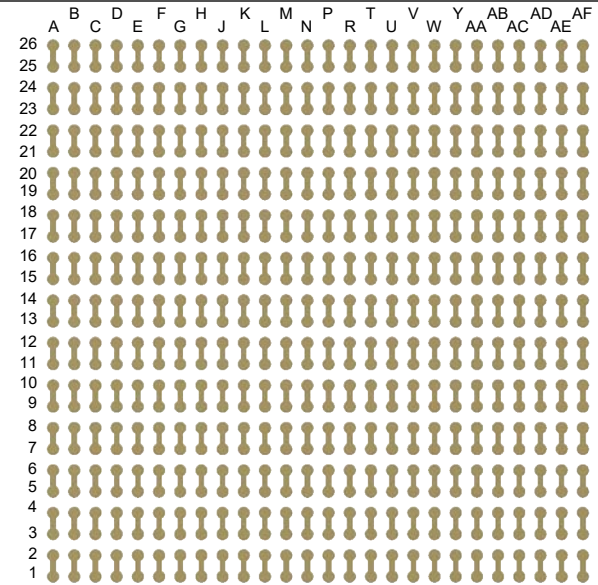
APPROVALS	DATE				
DRAWN T. Au	6/18/2023				
ENG M. Hart	6/18/2023	TITLE WLP676T.35C-DC260D 676 BALL P=0.35mm			
MFG		SCALE 40:1	SIZE A	DRAWING NO. 572600	REV A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

DAISY CHAIN PATTERN

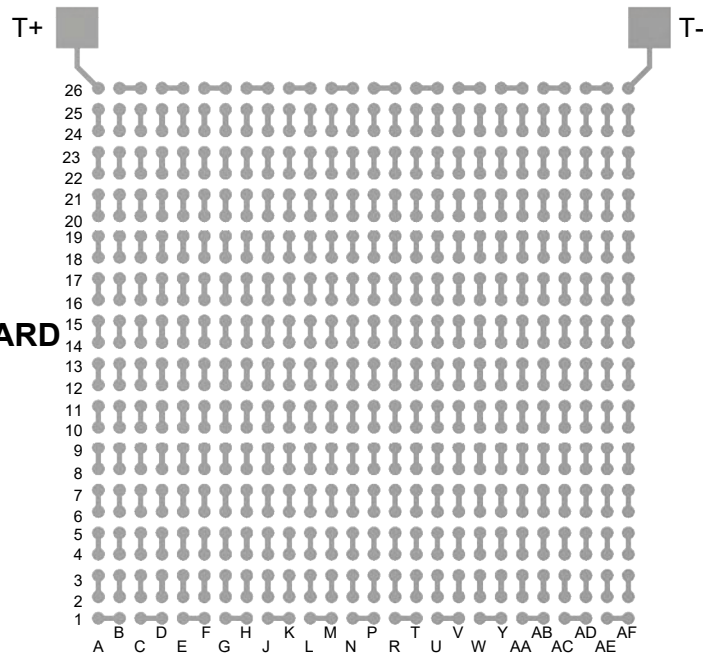
BALL VIEW



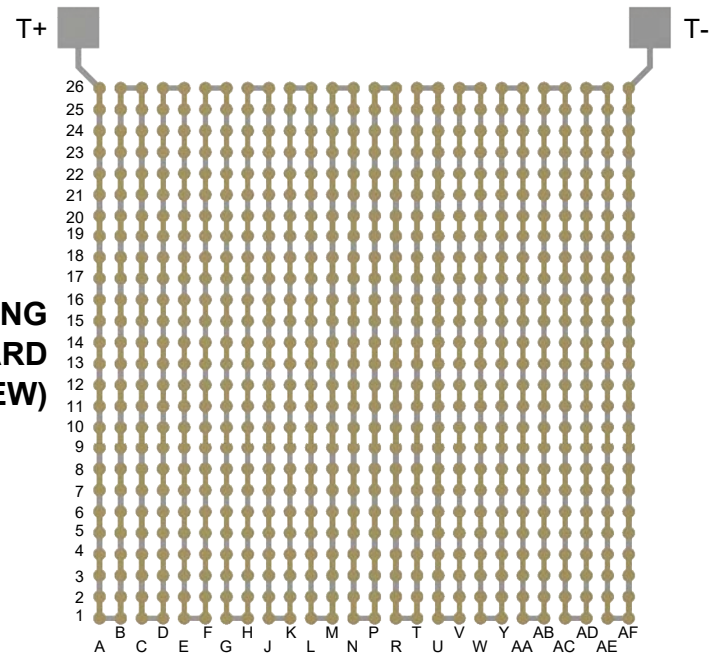
**BOTTOM SIDE
(TOP X-RAY VIEW)**



PC BOARD



**AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)**



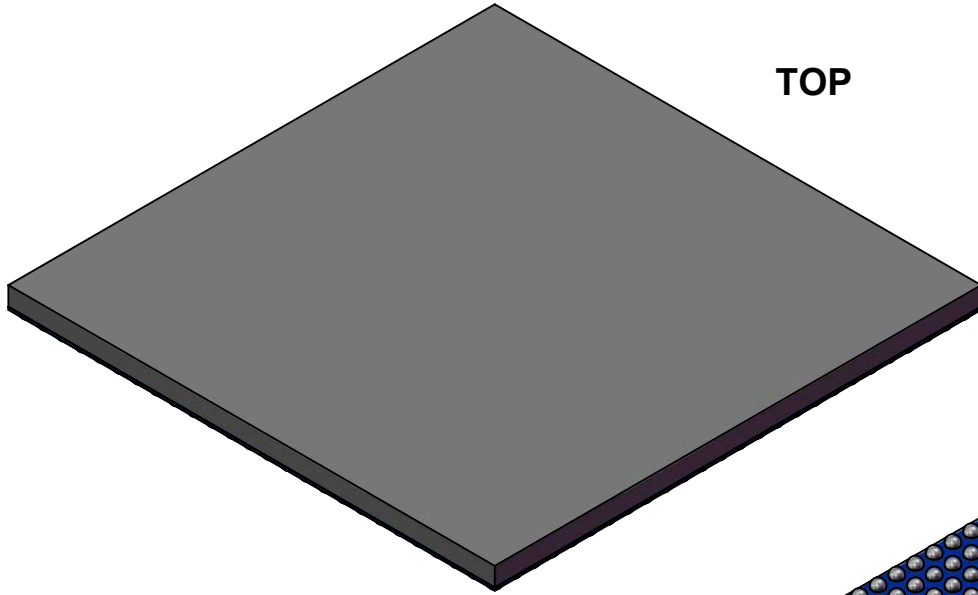
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: $\varnothing 0.21\text{mm}$ (8.2 mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.10mm (4 mil).

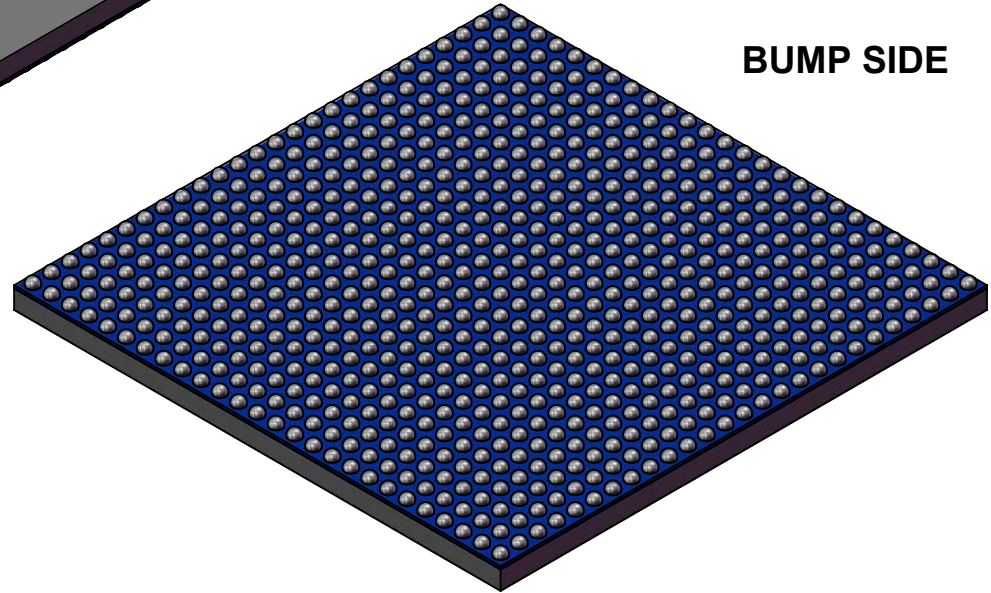
TopLine[®]			
TITLE		WLP676T.35C-DC260D 676 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
25:1	A	572600	A
DO NOT SCALE DRAWING			SHEET 2 OF 5

MODEL

TOP



BUMP SIDE



TopLine[®]

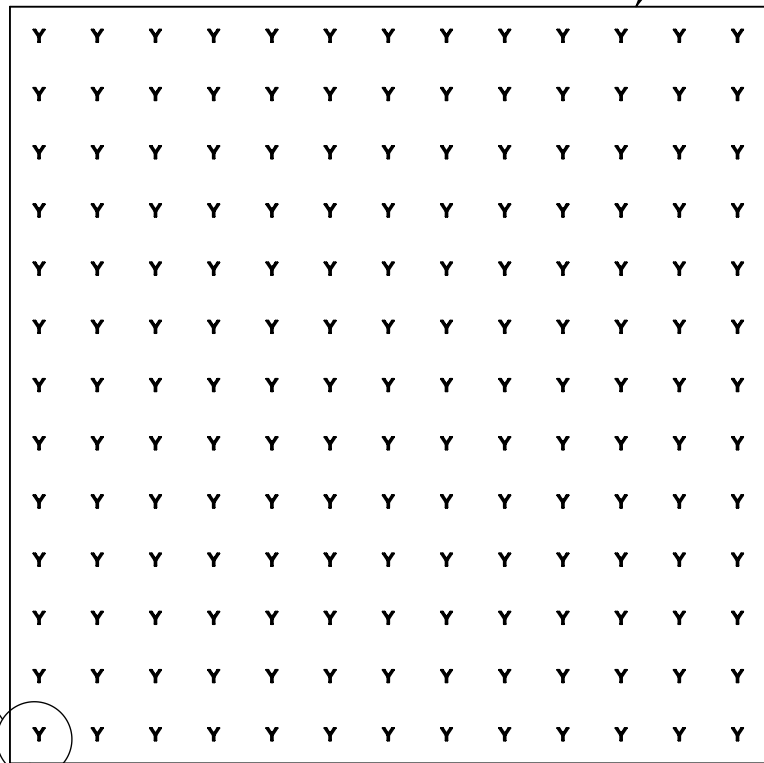
TITLE WLP676T.35C-DC260D
676 BALL P=0.35mm

SCALE	SIZE	DRAWING NO.	REV
40:1	A	572600	A

DO NOT SCALE DRAWING SHEET 3 OF 5

TOP VIEW

SILICON (Si)

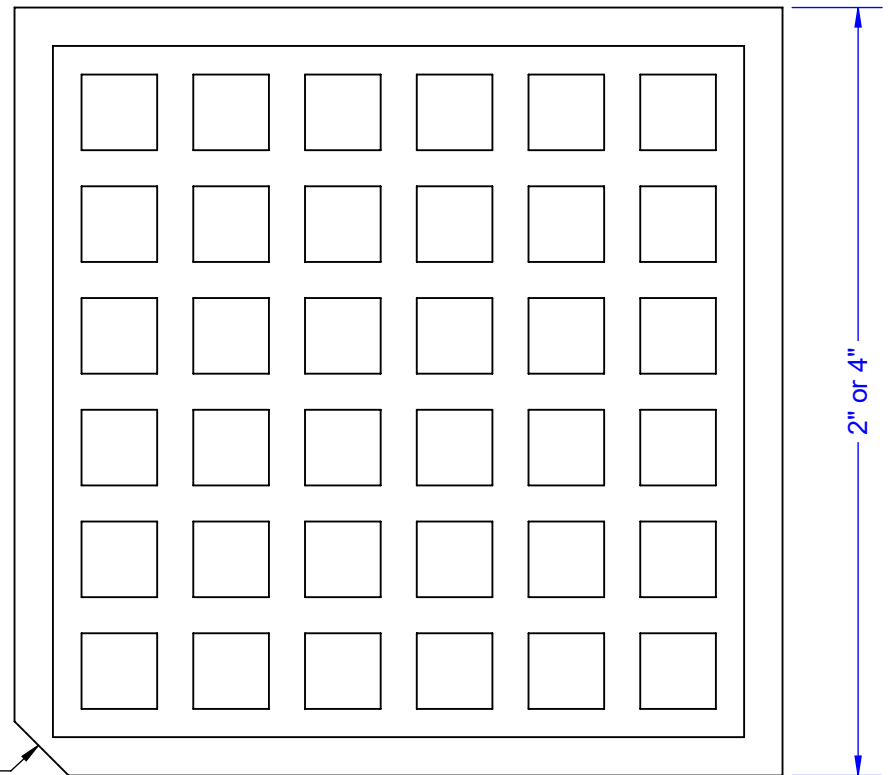


EXAMPLE ORIENTATION OF MARKING ON WLP

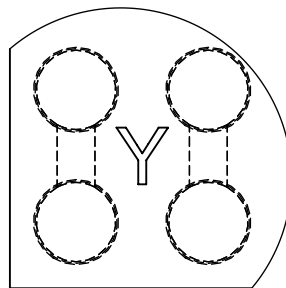
B

PIN 1

TYPICAL WAFFLE PACK IC CHIP TRAY SCALE = 2:1



NUMBER OF POCKETS WILL CHANGE BASED ON THE SIZE OF THE WLP CHIP



DAISY CHAIN ORIENTATION DETAIL B SCALE 50 : 1

Notes: (Unless Otherwise Specified).

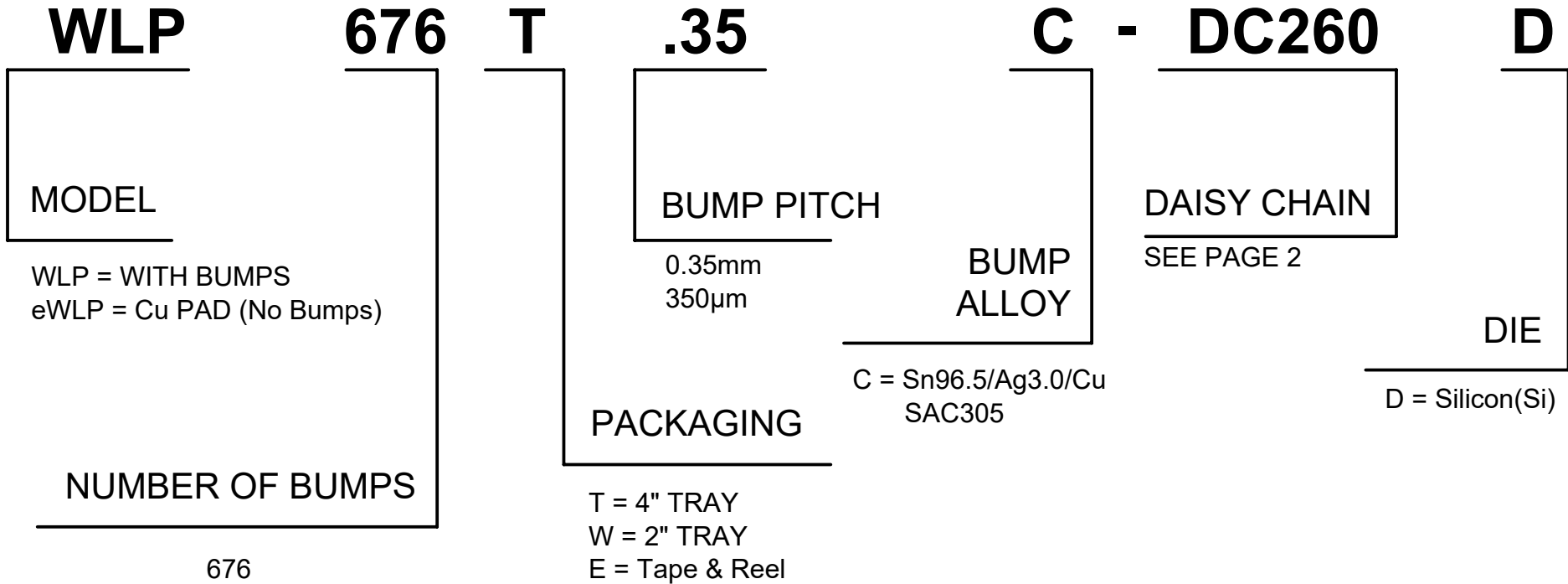
- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.

MARKING CODE	
PITCH	LETTER
0.35mm	Y

* SUBJECT TO CHANGE

TopLine®			
TITLE		WLP676T.35C-DC260D 676 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
30:1	A	572600	A
DO NOT SCALE DRAWING			SHEET 4 OF 5

PART NUMBER SYSTEM



PART NUMBER	PACKAING	QTY
WLP676W.35C-DC260D	2" CHIP TRAY	16
WLP676T.35C-DC260D	4" CHIP TRAY	49
WLP676E.35C-DC260D	T&R	500

TopLine[®]			
TITLE WLP676T.35C-DC260D 676 BALL P=0.35mm			
SCALE 30:1	SIZE A	DRAWING NO. 572600	REV A
DO NOT SCALE DRAWING		SHEET 5 OF 5	